

Discription

The VESD05A1-02V-G-08 protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.



SOD-523

Features

- ★ Small Body Outline Dimensions
- ★ Low Body Height
- ★ Peak Power up to 250 Watts @ 8 x 20 _s Pulse
- ★ Low Leakage current
- ★ Response Time is Typically < 1 ns</p>
- ★ ESD Rating of Class 3 (> 16 kV) per Human Body Model
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ IEC61000-4-4 Level 4 EFT Protection



Circuit Diagram

Orderingin formation

Product ID	Pack	Qty(PCS)
VESD05A1-02V-G-08	SOD-523	3000

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P_{PP}	Peak Pulse Power (t _p = 8/20μs)	250	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T_{op}	Operating Temperature Range	-40 to +125	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	±30 ±30	KV



Electrical Characteristics

Symbol	Parameter	neter Test Condition		Тур	Max	Units
V _{RWM}	Reverse Working Voltage				5.0	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA	6.5			V
I _R	Reverse Leakage Current	V _{RWM} = 5V			1.0	μΑ
Vc	Clamping Voltage	$I_{RWM} = 1A, t_p = 8/20 \mu s$		9.5		V
		$I_{RWM} = 15A, t_p = 8/20 \mu s$		20		V
Cı	Junction Capacitance	$V_R = 0V$, $f = 1MHz$		180		pF

Typical Characteristics

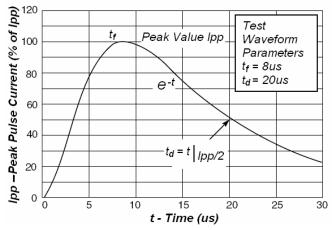


Fig1. Pulse Waveform

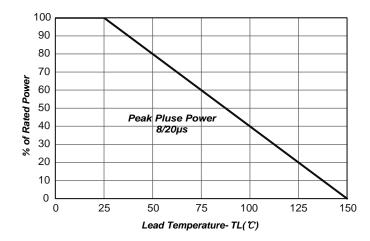
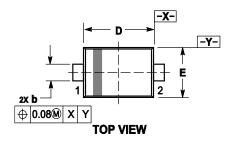
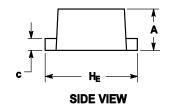


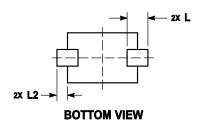
Fig2.Power Derating



Outline And Dimensions





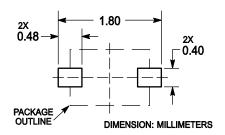


Notes:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS		INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
С	0.07	0.14	0.20	0.003	0.006	0.008
ם	1.10	1.20	1.30	0.043	0.047	0.051
Е	0.70	0.80	0.90	0.028	0.031	0.035
H _E	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF		0.012 REF			
L ₂	0.15	0.20	0.25	0.006	0.008	0.010

Soledering Footprint





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